

## CLAIMS

1. A photoresist base material comprising an extreme ultra-violet reactive organic compound represented by the following general formula (1),

$$\begin{pmatrix}
C & Y & A & Z & D & D & D
\end{pmatrix}_{n}$$
(1)

wherein A is a central structure that is an 10 aliphatic group having 1 to 50 carbon atoms, an aromatic group having 6 to 50 carbon atoms, an organic group containing said aliphatic group and said aromatic group together or an organic group having a cyclic structure formed by repetition of these groups, each of B, C and D is independently an extreme ultra-violet reactive group, a group having reactivity to the action of chromophore active to extreme ultra-violet, or a  $C_1$  to  $C_{50}$  aliphatic group,  $C_6$ to  $C_{50}$  aromatic group, an organic group containing said aliphatic group and said aromatic group together or a 20 substituent having a branched structure, containing such a reactive group, each of X, Y and Z is independently a single bond or an ether bond, each of 1, m and n is independently an integer of 0 to 5 satisfying  $1 + m + n \ge 1$ , and A, B, C and D may contain a substituent having a heteroatom.

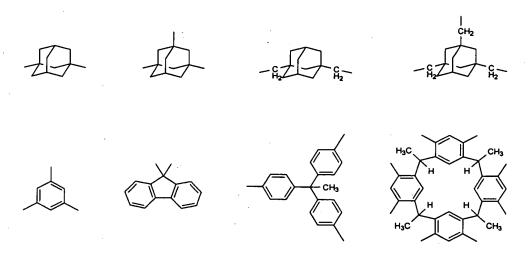
- The photoresist base material as recited in claim 1,
   wherein said organic compound reactive to extreme ultraviolet is in an amorphous state at room temperature and has a molecule whose average diameter is 2 nm or less.
- 3. The photoresist base material as recited in claim 1 or 2, wherein A is an organic group represented by

each of B, C and D is an extreme ultra-violet reactive group, a group having reactivity to the action of chromophore active to extreme ultra-violet, or an organic group represented by

wherein Ar is a phenyl or naphthyl group substituted with RO- and/or ROCO- in which R, RO- and ROCO 5 are extreme ultra-violet reactive groups or groups having reactivity to the action of a chromophore active to extreme ultra-violet, and

X, Y and Z are ether bonds.

10 4. The photoresist base material as recited in claim 3, wherein A is an organic group represented by



each of B, C and D is a hydrogen atom, tert-butyl,

15 tert-butyloxycarbonylmethyl, tert-butyloxycarbonyl, 1tetrahydropyranyl, 1-tetrahydrofuranyl, 1-ethoxyethyl, 1phenoxyethyl, an organic group represented by

$$-\left(\begin{array}{c}H_2\\C\end{array}\right)_{S}P-\left(\begin{array}{c}O\\O-C\\O-O-Q\end{array}\right)_{\Gamma}$$

in which P is an aromatic group having a valence of (r + 1) and having 6 to 20 carbon atoms, Q is an organic group having 4 to 30 carbon atoms, r is an integer of 1 to 10 and s is an integer of 0 to 10, or an organic group represented by

in which Ar is a phenyl or naphthyl group substituted with RO- and/or ROCO- in which R is hydrogen, tert-butyl, tert-butyloxycarbonylmethyl, tert-

butyloxycarbonyl, 1-tetrahydropyranyl, 1-tetrahydrofuranyl,
1-ethoxyethyl, 1-phenoxyethyl, an organic group represented
by

$$-\left(\begin{array}{c} H_2 \\ C \end{array}\right)_{S} P - \left(\begin{array}{c} O \\ O - C - O - Q \end{array}\right)_{\Gamma}$$

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in which P is an aromatic group having a valence of (r + 1) and having 6 to 20 carbon atoms, Q is an organic group having 4 to 30 carbon atoms, r is an integer of 1 to 10 and s is an integer of 0 to 10,

and X, Y and Z are ether bonds.

5. The photoresist base material as recited in claim 4,

wherein A is an organic group represented by

each of B, C and D is a hydrogen atom, tert-butyl,

5 tert-butyloxycarbonylmethyl, tert-butyloxycarbonyl, 1tetrahydropyranyl, 1-tetrahydrofuranyl, 1-ethoxyethyl, 1phenoxyethyl or an organic group represented by

$$\frac{-\left(\begin{array}{c}H_2\\C\end{array}\right)_{S}P-\left(\begin{array}{c}O\\O-C\\O-Q\end{array}\right)_{I}$$

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in which P is an aromatic group having a valence of (r+1) and having 6 to 20 carbon atoms, Q is an organic group having 4 to 30 carbon atoms, r is an integer of 1 to 10 and s is an integer of 0 to 10,

and X, Y and Z are ether bonds.

6. A photoresist base material comprising a radiation-sensitive organic compound represented by the following general formula (1),

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$$\begin{pmatrix}
C
\end{pmatrix}_{m}
\begin{pmatrix}
C
\end{pmatrix}_{m}
\begin{pmatrix}
C
\end{pmatrix}_{n}$$
(1)

wherein A is an organic group represented by

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each of B, C and D is independently an organic group represented by

$$-\frac{H_2}{C} + \frac{O}{S} P - \left(O - C - O - Q\right)_{\Gamma}$$

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in which P is an aromatic group having a valence of (r + 1) and having 6 to 20 carbon atoms, Q is an organic 15 group having 4 to 30 carbon atoms, r is an integer of 1 to 10 and s is an integer of 0 to 10, and

$$1 + m + n = 3 \text{ or } 8.$$

7. The photoresist base material as recited in claim 6, wherein the organic group represented by

$$-\left(\begin{matrix} H_2 \\ C \end{matrix}\right)_S P - \left(\begin{matrix} O \\ II \end{matrix} - O - Q \begin{matrix} O \\ II \end{matrix}\right)_T$$

is 4-(tert-butoxycarbonyloxy)benzyl or 3,5-di(tert-butoxycarbonyloxy)benzyl.

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- 10 8. The photoresist base material as recited in claim 6, wherein the radiation is extreme ultra-violet or electron beam.
- 9. The photoresist base material as recited in any one 15 of claims 1 to 8, wherein at least one of B, C and D is a hydrogen atom and X, Y and Z are ether bonds.
- 10. The photoresist base material as recited in any one of 1 to 8, which has a basic impurity content of 10 ppm or 20 less.
  - 11. A photoresist composition containing a solid content containing the photoresist base material recited in any one of claims 1 to 8 and a solvent.

12. A photoresist composition comprising a solid content containing the photoresist base material recited in claim 10 and a solvent.

- 13. The photoresist composition as recited in claim 11 or 12, which further contains an optically-acid-generating agent.
- A method for purification of a photoresist base material, which comprises washing the photoresist base material recited in any one of claims 1 to 8 with an acidic aqueous solution and treating the material with an ion-exchange resin.

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- 15. The method for purification of a photoresist base material as recited in claim 14, wherein said acidic aqueous solution is an acetic acid aqueous solution.
- 15 16. A method for improvement of the photoresist base material recited in any one of claims 1 to 8 in radiation sensitivity, which comprises decreasing the content of basic impurities to 10 ppm or less.
- 20 17. A method for fine processing by lithography, which uses the photoresist composition recited in claim 11 or 12.
  - 18. A semiconductor device fabricated using the photoresist composition recited in claim 11 or 12.

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19. An organic compound represented by the following general formula (1),

$$\begin{pmatrix}
C
\end{pmatrix}_{m}^{A}
\begin{pmatrix}
Z
\end{pmatrix}_{D}$$
(1)

wherein A is an organic group represented by

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$$-\left(\begin{matrix} H_2 \\ C \end{matrix}\right)_S P - \left(\begin{matrix} O \\ O - C - O - Q \end{matrix}\right)_T$$

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in which P is an aromatic group having a valence of (r+1) and having 6 to 20 carbon atoms, Q is an organic group having 4 to 30 carbon atoms, r is an integer of 1 to 10 and s is an integer of 0 to 10,

15 and

1 + m + n = 3 or 8.

- 20. The organic compound as recited in claim 19, which has a basic impurity content of 10 ppm or less.
- 21. A method for purification of an organic compound, which comprises washing the organic compound recited in claim 19 with an acidic aqueous solution and treating the compound with an ion-exchange resin.